

MEG03-005



appl. no. 10/796,427

May 11, 2007

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/796,427	03/09/04
MOU-SHIUNG LIN		
“WIREBOND PAD FOR SEMICONDUCTOR CHIP OR WAFER”		
Grp. Art Unit: 2822	LEWIS, MONICA	

#### RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action mailed February 12, 2007, please consider the remarks as follows:

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 14, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 5/14/07